

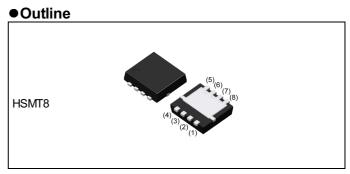
# RQ3P300BH

Nch 100V 39A Power MOSFET

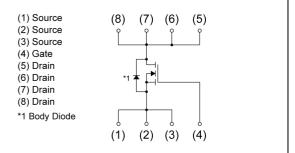
V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	15.5mΩ
I <sub>D</sub>	±39A
P <sub>D</sub>	32W

# Features

- 1) Low on resistance
- 2) Small Surface Mount Package
- 3) Pb-free plating ; RoHS compliant



# ●Inner circuit



# Packaging specifications

		Packing	Embossed Tape
		Reel size (mm)	330
● Application	Туре	Tape width (mm)	12
Primary side switch		Quantity (pcs)	3000
Moter drives		Taping code	TB1
DC/DC converter		Marking	P300BH

# • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit		
Drain - Source voltage		V <sub>DSS</sub>	100	V	
Continuous drain surrant	$V_{} = 10V_{}$	۱ <sub>D</sub> *1	±39	А	
Continuous drain current	V <sub>GS</sub> = 10V	Ι <sub>D</sub>	±10	А	
Pulsed drain current	۱ <sub>DP</sub> *2	±40	А		
Gate - Source voltage		V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	10	А		
Avalanche energy, single pulse		$E_{AS}^{*3}$	40	mJ	
Power dissipation		P <sub>D</sub> <sup>*1</sup>	32	W	
		P <sub>D</sub> <sup>*4</sup>	2.0	W	
Junction temperature		Tj	150	°C	
Operating junction and storage te	T <sub>stg</sub>	-55 to +150	C°		

# •Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	3.9	°C/W
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	-	62.5	°C/W

# • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions	Values			Linit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = 1 \text{mA}$ referenced to 25°C		62.3	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	10	μA	
Gate - Source leakage current	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1mA$	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient $\Delta V_{GS(th)}$ $\Delta T_j$		I <sub>D</sub> = 1mA referenced to 25°C	-	-4.5	-	mV/°C	
Static drain - source	<b>D</b> *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	11.9	15.5		
on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	V <sub>GS</sub> = 6V, I <sub>D</sub> = 10A	-	15.6	24.0	mΩ	
Gate resistance	R <sub>G</sub> -		0.9	1.7	3.4	Ω	
Forward Transfer Admittance $ Y_{fs} ^{*5}$ $V_{DS} = 5V$ , $I_D = 10A$		8.8	-	-	S		

 $*1T_c = 25^{\circ}C$ , Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.5mH, V\_{DD} = 50V, R\_G = 25\Omega, Starting T\_j = 25°C Fig.3-1,3-2

- \*4 Mounted on a Cu board (40×40×0.8mm)
- \*5 Pulsed



# • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Parameter	Symbol Conditions		Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	*510	1020	*2040	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 50V	*115	230	*460	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	*8.5	17	*34	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 50V, V_{GS} = 10V$	-	18	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 5A	-	20	-	no
Turn - off delay time	$t_{d(off)}$ *5	$R_L \simeq 10\Omega$	-	34	-	ns
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	14	-	

\*: Guarantee of Design

# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

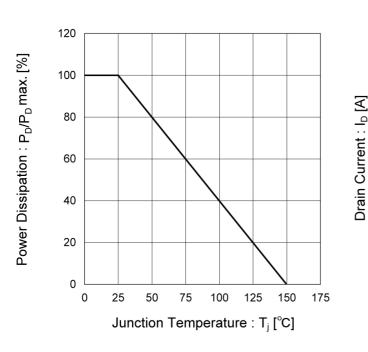
Parameter	Symbol Conditions		Values			Unit
			Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 50V,	*9.0	18.0	*36.0	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 10A,	*2.2	4.4	*8.8	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	*2.6	5.2	*10.4	

\*: Guarantee of Design

# • Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Symbol Conditions		Values			Unit
Parameter			Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	$T = 25^{\circ}$ C	-	-	1.67	А
Pulse forward current	1 <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	40	А
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10A, V <sub>GS</sub> =0V	-	48	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	31	-	nC





# Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

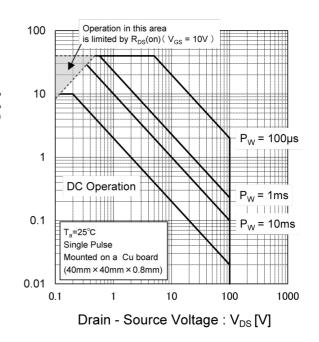
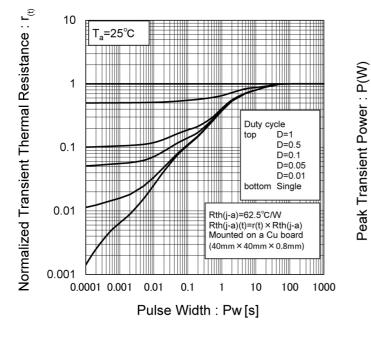


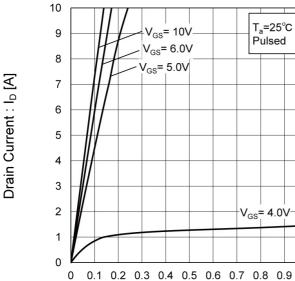
Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power Dissipation



 $10000 \\ T_a = 25^{\circ}C \\ Single Pulse \\ 1000 \\ 100 \\$ 

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# Fig.5 Typical Output Characteristics(I)

V<sub>GS</sub>= 10V

V<sub>GS</sub>= 6.0V

V<sub>GS</sub>= 5.0V

T<sub>a</sub>=25°C

Pulsed

V<sub>GS</sub>= 4.0V

1

Fig.6 Typical Output Characteristics(II)

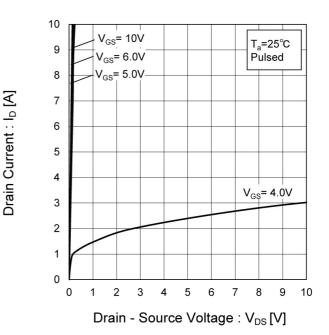
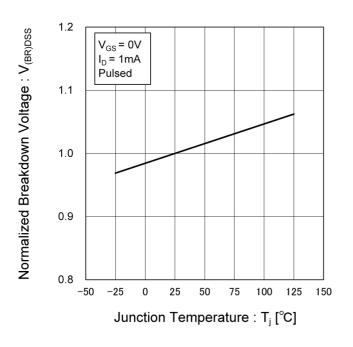
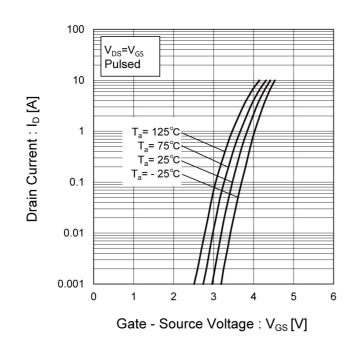


Fig.7 Breakdown Voltage vs. **Junction Temperature** 

Drain - Source Voltage : V<sub>DS</sub> [V]

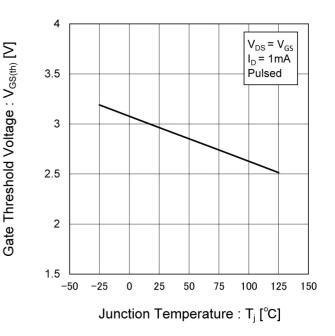




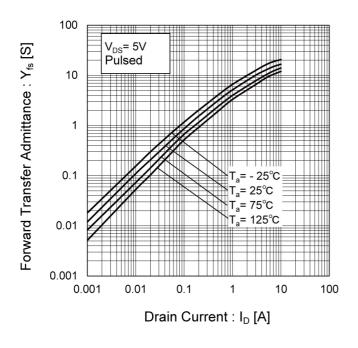


# Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature



# Fig.10 Forward Transfer Admittance vs. Drain Current





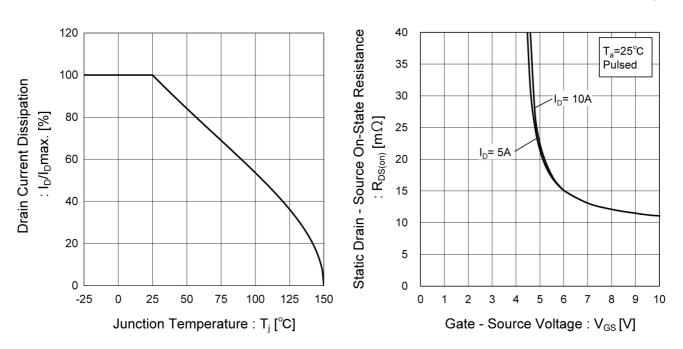
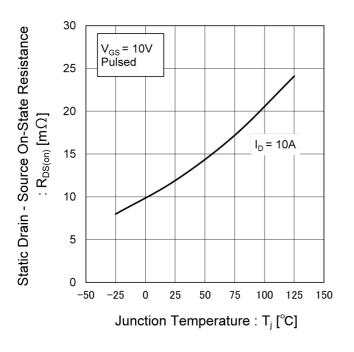


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





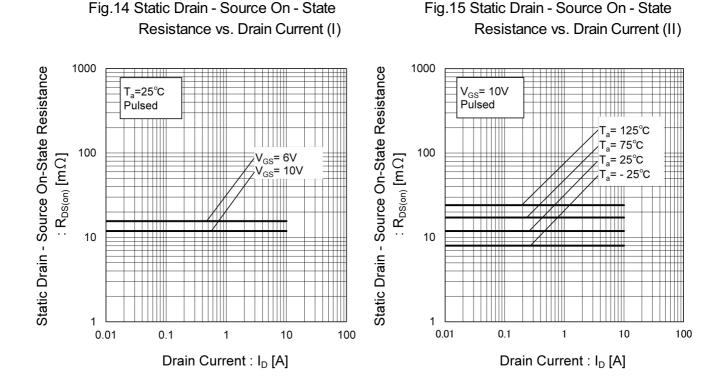
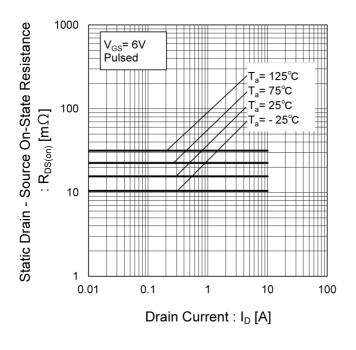


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



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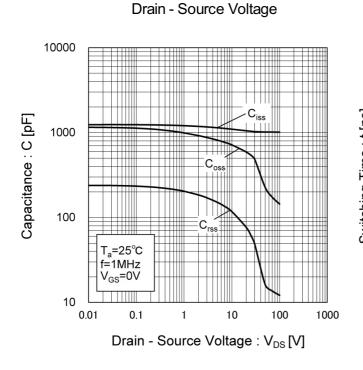


Fig.17 Typical Capacitances vs.

# Fig.18 Switching Characteristics

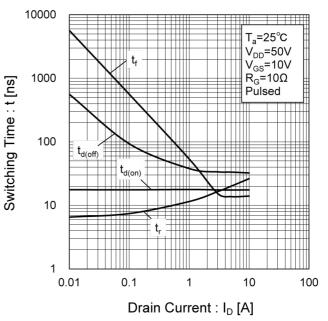


Fig.19 Typical Gate Charge

Gate - Source Voltage : V<sub>GS</sub> [V]

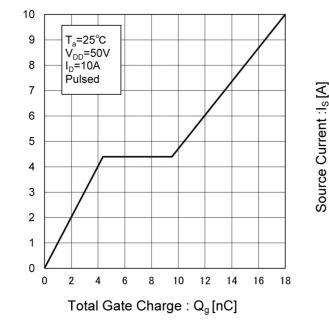
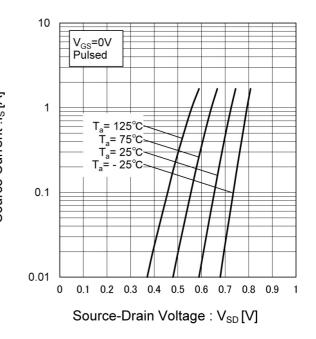


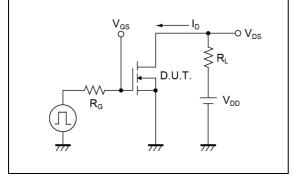
Fig.20 Source Current vs. Source Drain Voltage



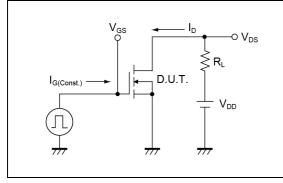
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# Measurement circuits

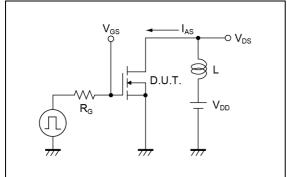
Fig.1-1 Switching Time Measurement Circuit



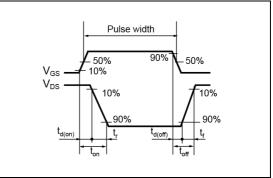
### Fig.2-1 Gate Charge Measurement Circuit



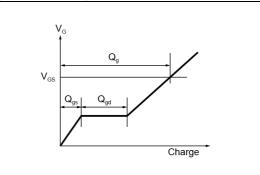
## Fig.3-1 Avalanche Measurement Circuit



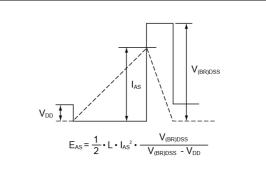
#### Fig.1-2 Switching Waveforms



### Fig.2-2 Gate Charge Waveform



## Fig.3-2 Avalanche Waveform



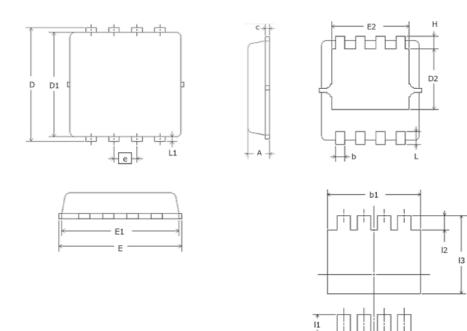
# Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



# Dimensions

HSMT8 (TB1) (3.3x3.3)



l e l Refarenced footprint dimensions

b2

14

	Milim	eters	Incl	hes	
DIM	Min.	Max.	Min.	Max.	
A	0.70	0.80	0.028	0.031	
b	0.25	0.35	0.010	0.014	
с	0.10	0.25	0.004	0.010	
D	3.25	3.45	0.128	0.136	
D1	3.00	3.20	0.118	0.126	
D2	1.78	1.98	0.070	0.078	
E	3.20	3.40	0.126	0.134	
E1	3.00	3.20	0.118	0.126	
E2	2.39	2.59	0.094	0.102	
е	0.	65	0.0	26	
н	0.30	0.50	0.012	0.020	
L	0.30	0.50	0.012	0.020	
L1	0.13		0.0	05	
	N.C.C.	-+	Le al		

	Milimeters	Inches
	Nom.	Nom.
11	0.60	0.024
12	0.45	0.018
13	2.45	0.096
14	3.70	0.146
b1	3.00	0.118
b2	0.43	0.017

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Dimension in mm/inches

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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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